

DS3680 QUAD TELEPHONE RELAY DRIVER

SLRS014C – MARCH 1986 – REVISED SEPTEMBER 1995

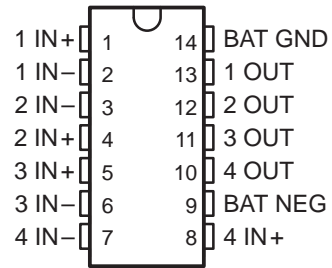
- Designed for –52-V Battery Operation
- 50-mA Output Current Capability
- Input Compatible With TTL and CMOS
- High Common-Mode Input Voltage Range
- Very Low Input Current
- Fail-Safe Disconnect Feature
- Built-in Output Clamp Diode
- Direct Replacement for National DS3680 and Fairchild μ A3680

description

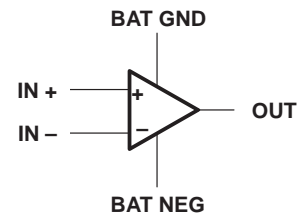
The DS3680 telephone relay driver is a monolithic integrated circuit designed to interface –48-V relay systems to TTL or other systems in telephone applications. It is capable of sourcing up to 50 mA from standard –52-V battery power. To reduce the effects of noise and IR drop between logic ground and battery ground, these drivers are designed to operate with a common-mode input range of ± 20 V referenced to battery ground. The common-mode input voltages for the four drivers can be different, so a wide range of input elements can be accommodated. The high-impedance inputs are compatible with positive TTL and CMOS levels or negative logic levels. A clamp network is included in the driver outputs to limit high-voltage transients generated by the relay coil during switching. The complementary inputs ensure that the driver output is off as a fail-safe condition when either output is open.

The DS3680 is characterized for operation from 0°C to 70°C.

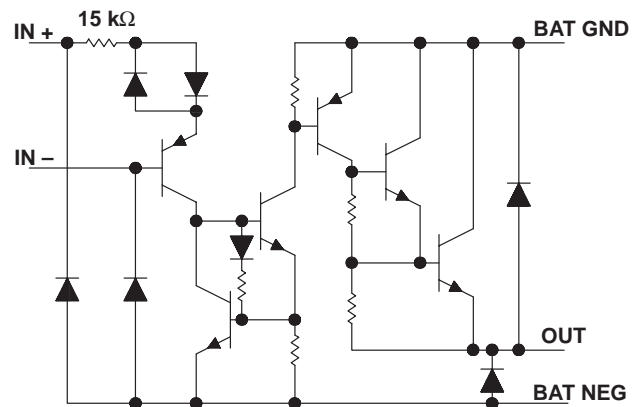
D OR N PACKAGE
(TOP VIEW)



symbol (each driver)



schematic diagram (each driver)



All resistor values shown are nominal.

DS3680 QUAD TELEPHONE RELAY DRIVER

SLRS014C – MARCH 1986 – REVISED SEPTEMBER 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range at BAT NEG, V_{BAT-} (see Note 1)	-70 V to 0.5 V
Input voltage range with respect to BAT GND	-70 V to 20 V
Input voltage range with respect to BAT NEG	-0.5 V to 70 V
Differential input voltage, V_{ID} (see Note 2)	± 20 V
Output current, I_O : Resistive load	-100 mA
Inductive load	-50 mA
Inductive output load	5 H
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	260°C

- NOTES: 1. All voltages are with respect to BAT GND, unless otherwise specified.
2. Differential input voltages are at the noninverting input terminal IN+ with respect to the inverting input terminal IN-.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW
N	1150 mW	9.2 mW/°C	736 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{BAT-}	-10	-60	V
Input voltage, either input	-20†	20	V
High-level differential input voltage, V_{IDH}	2	20	V
Low-level differential input voltage, V_{IDL}	-20†	0.8	V
Operating free-air temperature, T_A	0	70	°C

† The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for input voltage levels.

electrical characteristics over recommended operating free-air temperature range, $V_{BAT-} = -52$ V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT			
I_{IH}	High-level input current (into IN+)	$V_{ID} = 2$ V		40	100	μA			
		$V_{ID} = 7$ V		375	1000				
I_{IL}	Low-level input current (into IN+)	$V_{ID} = 0.4$ V		0.01	5	μA			
		$V_{ID} = -7$ V		-1	-100				
$V_{O(on)}$	On-stage output voltage	$I_O = 50$ mA, $V_{ID} = 2$ V	-1.6		-2.1	V			
$I_{O(off)}$	Off-stage output current	$V_O = V_{BAT-}$ Inputs open				$V_{ID} = 0.8$ V	-2	-100	μA
							-2	-100	
I_R	Clamp diode reverse current	$V_O = 0$		2	100	μA			
V_{OK}	Output clamp voltage	$I_O = 50$ mA		0.9	1.2	V			
		$I_O = -50$ mA, $V_{BAT-} = 0$		-0.9	-1.2				
$I_{BAT(on)}$	On-state battery current	All drivers on		-2	-4.4	mA			
$I_{BAT(off)}$	Off-state battery current	All drivers off		-1	-100	μA			

‡ All typical values are at $T_A = 25^\circ\text{C}$.



switching characteristics $V_{BAT-} = -52\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{on}	Turn-on time	$V_{ID} = 3\text{-V pulse}$, $R_L = 1\text{ k}\Omega$, $L = 1\text{ H}$, See Figure 2		1	10	μs
t_{off}	Turn-off time			1	10	μs

PARAMETER MEASUREMENT INFORMATION

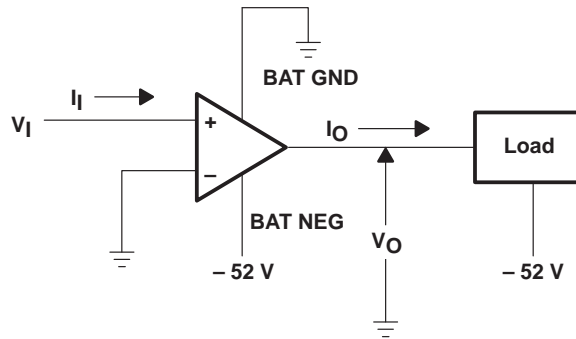


Figure 1. Generalized Test Circuit, Each Driver

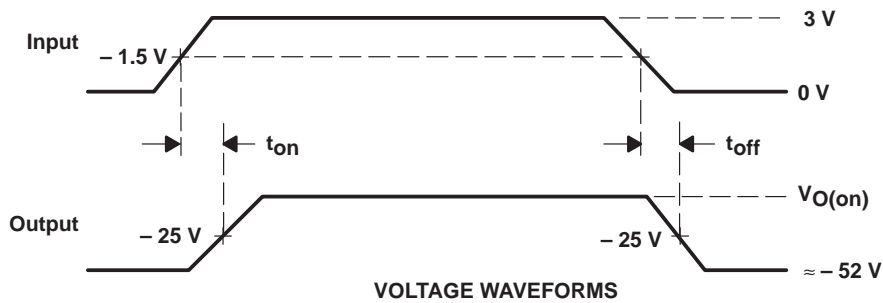
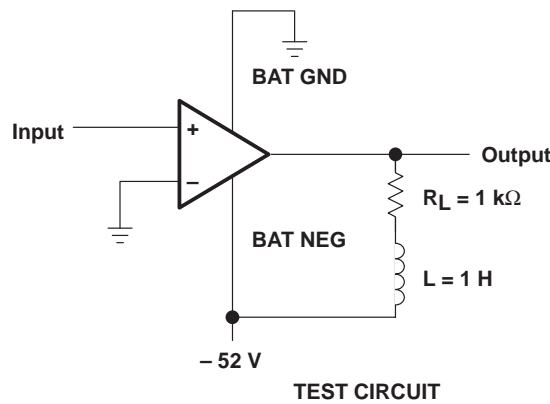


Figure 2. Test Circuit and Voltage Waveforms, Each Driver

DS3680 QUAD TELEPHONE RELAY DRIVER

SLRS014C – MARCH 1986 – REVISED SEPTEMBER 1995

APPLICATION INFORMATION

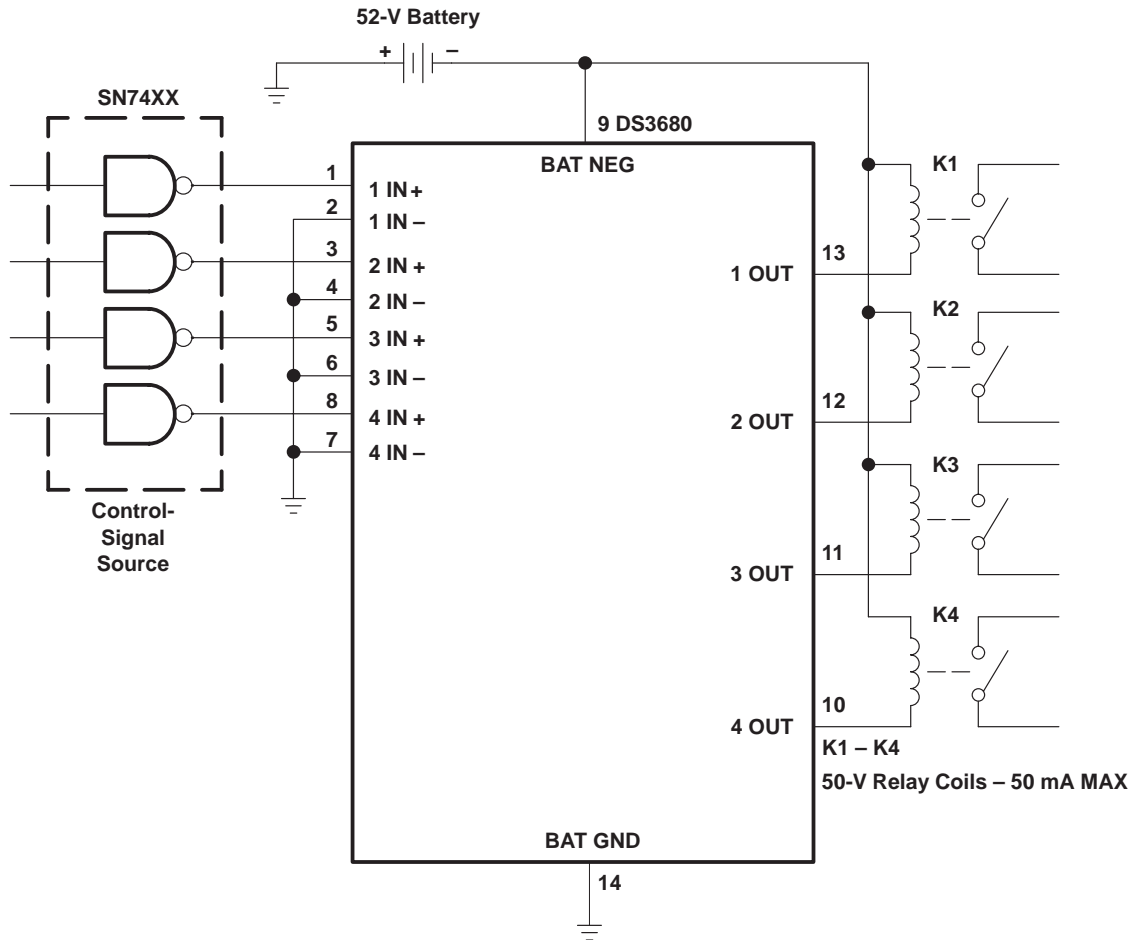


Figure 3. Relay Driver

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
DS3680D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
DS3680N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
DS3680NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS3680DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS3680DR	SOIC	D	14	2500	367.0	367.0	38.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com